



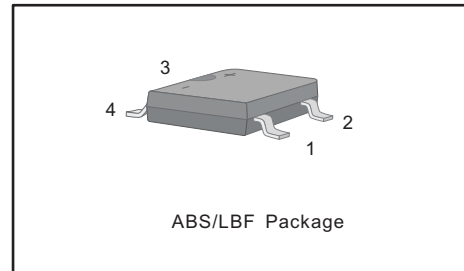
1A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 1400 V
- Forward Current - 1A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



MECHANICAL DATA

- Case: ABS/LBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 88mg / 0.0031oz
- Chip size: 50mil

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	ABS14-10	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1400	V
Maximum RMS voltage	V_{RMS}	980	V
Maximum DC Blocking Voltage	V_{DC}	1400	V
Average Rectified Output Current at $T_c = 125\text{ }^\circ\text{C}$	I_o	1	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30	A
Forward Voltage per element @ $I_F = 1\text{ A}$	V_F	1.1	V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_A = 25\text{ }^\circ\text{C}$ @ $T_A = 125\text{ }^\circ\text{C}$	I_R	3 100	μA
Typical Junction Capacitance (Note1)	C_j	13	pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$ $R_{\theta JC}$	72 20	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.



Fig.1 Average Rectified Output Current Derating Curve

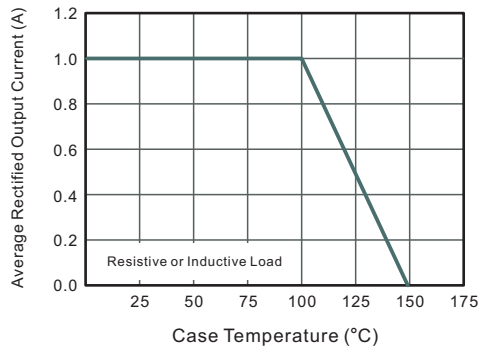


Fig.2 Typical Reverse Characteristics

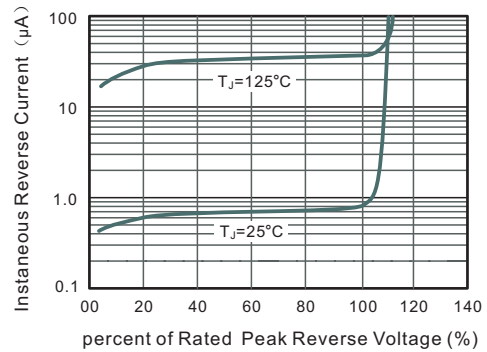


Fig.3 Typical Instantaneous Forward Characteristics

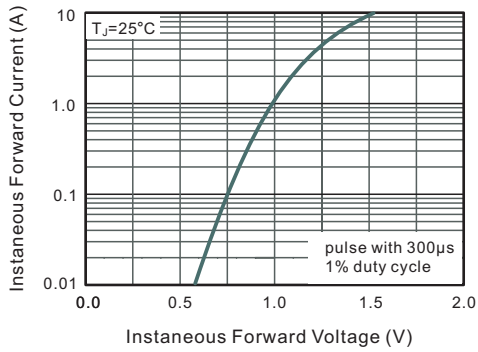


Fig.4 Typical Junction Capacitance

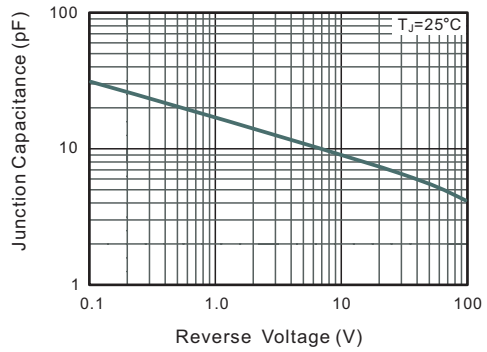
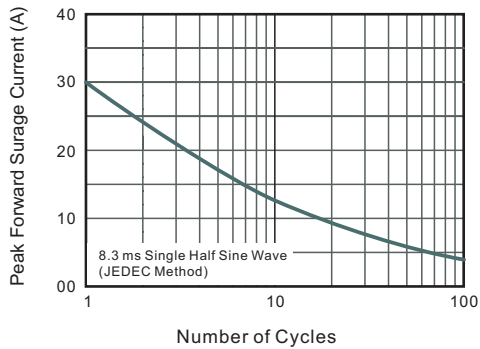


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

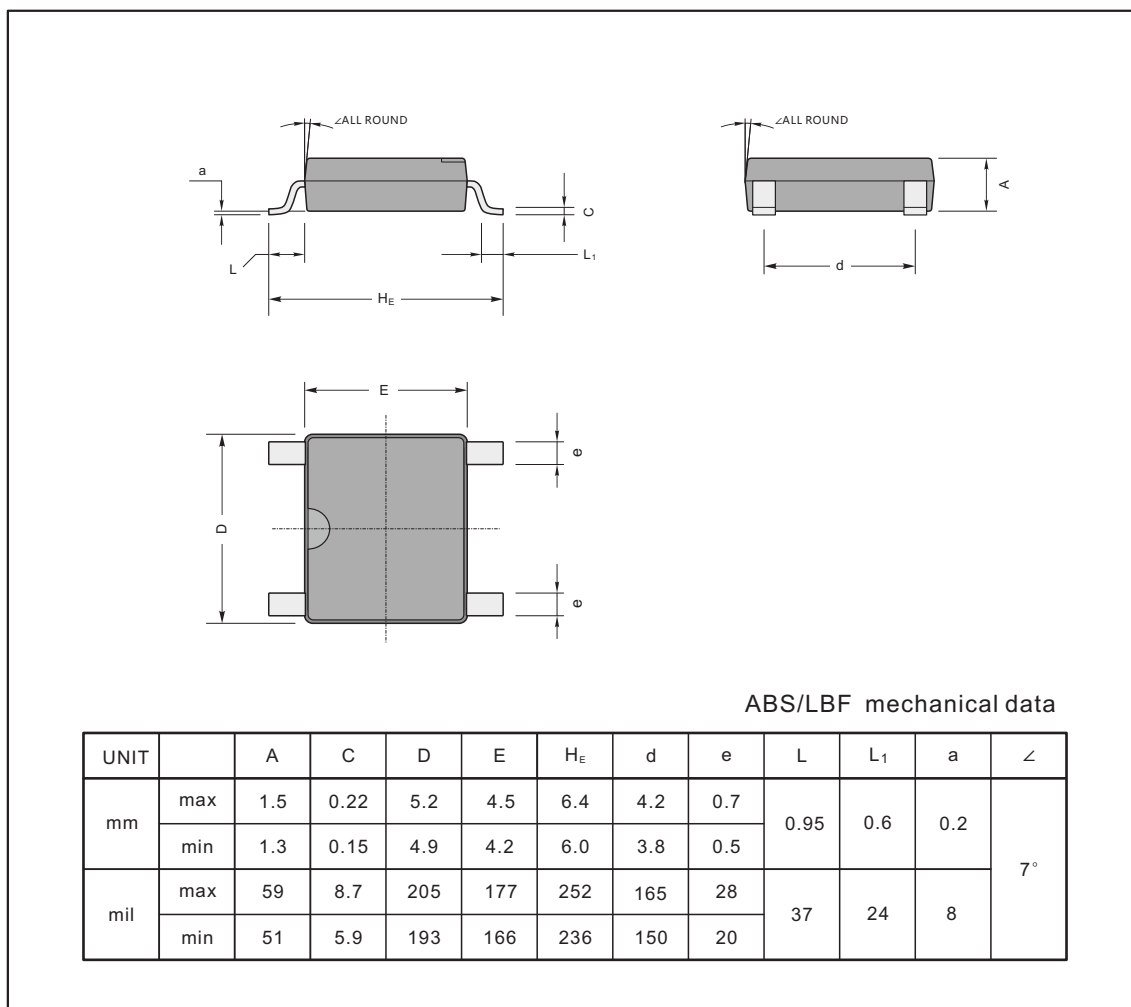




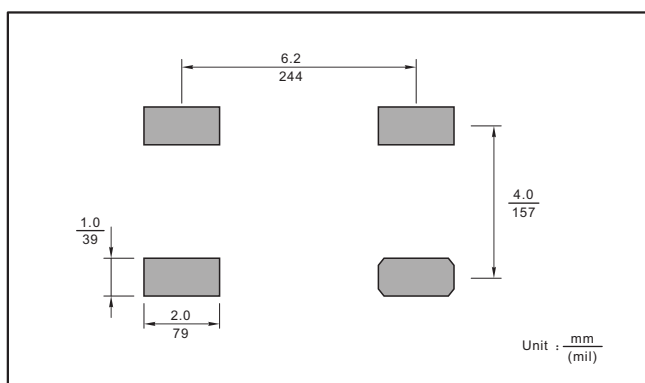
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

ABS/LBF



The recommended mounting pad size



Marking

Type number	Marking code
ABS14-10	10T14



文件履历表

序号	制/修订日期	生效日期	版次	修订内容	变更原因	制/修订人	备注
01	2022.8.30	2022.8.	Rev 1.1	初版制定	/	张雷	



Important Notice and Disclaimer

Jingdao Microelectronics reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.

Jingdao Microelectronics makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Jingdao Microelectronics assume any liability for application assistance or customer product design.

Jingdao Microelectronics does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.

No license is granted by implication or otherwise under any intellectual property rights of Jingdao Microelectronics.

Jingdao Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of Jingdao Microelectronics.